#### **FEE TRANSMITTAL**

## Electronic Version v08

Stylesheet Version v08.0

Title of Invention CHIP STRUCTURE WITH BUMPS AND A PROCESS FOR FABRICATING THE SAME

Application Number:

Date:

First Named Applicant: Mr. Chao-Fu Weng
Attorney Docket Number: 8012-US-PA-1

# **TOTAL FEE AUTHORIZED \$ 770**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

### **BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$			
Utility Filing Fee	1001	770	770			
Subtotal For Basic Filing Fees: \$ 770						

## **EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$		
Total Claims: 14	0	1202	18	0		
Independent Claims : 3	0	1201	86	0		
Subtotal For Extra Claims Fees: \$ 0						

### **AUTHORIZED BILLING INFORMATION**

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Credit account number: 1007

Expiration Date (YYYYMMDD): 2005-12-31

Authorized name: YEH, WEN-HUNG

Billing address: 99999